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(54) **SEMICONDUCTOR DEVICE WITH  
COMPARTMENT SHIELD FORMED FROM  
METAL BARS AND MANUFACTURING  
METHOD THEREOF**

(71) Applicant: **STATS ChipPAC Pte. Ltd.**, Singapore  
(SG)

(72) Inventors: **YongKook Shin**, Gyeonggi-do (KR);  
**KyoWang Koo**, Incheon (KR);  
**HeeYoun Kim**, Incheon (KR);  
**SeongKuk Kim**, Gyeonggi-do (KR)

(73) Assignee: **STATS ChipPAC Pte. Ltd.**, Singapore  
(SG)

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(57) **ABSTRACT**

A semiconductor device has a substrate and first and second electrical component disposed over the substrate. A first metal bar is disposed over the substrate between the first electrical component and second electrical component. The first metal bar is formed by disposing a mask over a carrier. An opening is formed in the mask and a metal layer is sputtered over the mask. The mask is removed to leave the metal layer within the opening as the first metal bar. The first metal bar can be stored in a tape-and-reel.

